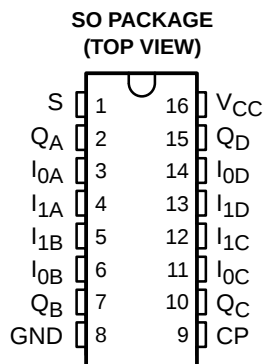


- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Fully Compatible With TTL Input and Output Logic Levels
- 64-mA Output Sink Current
32-mA Output Source Current



description

The CY74FCT399T is a high-speed quad 2-input register that selects four bits of data from either of two sources (ports) under control of a common select (S) input. Selected data are transferred to a 4-bit output register synchronous with the low-to-high transition of the clock (CP) input. The 4-bit D-type output register is fully edge triggered. The data inputs (I_{0X} , I_{1X}) and S input must be stable only one setup time prior to, and hold time after, the low-to-high transition of CP for predictable operation. The CY74FCT399T has noninverted outputs.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

PIN DESCRIPTION

NAME	DESCRIPTION
S	Common select input
CP	Clock-pulse input (active rising edge)
I ₀	Data inputs from source 0
I ₁	Data inputs from source 1
Q	Register noninverted outputs

ORDERING INFORMATION

T _A	PACKAGE [†]		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – SO	Tube	6.1	CY74FCT399CTSOC	FCT399C
		Tape and reel	6.1	CY74FCT399CTSOCT	
	SOIC – SO	Tube	7	CY74FCT399ATSOC	FCT399A
		Tape and reel	7	CY74FCT399ATSOCT	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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INSTRUMENTS

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CY74FCT399T
QUAD 2-INPUT REGISTER

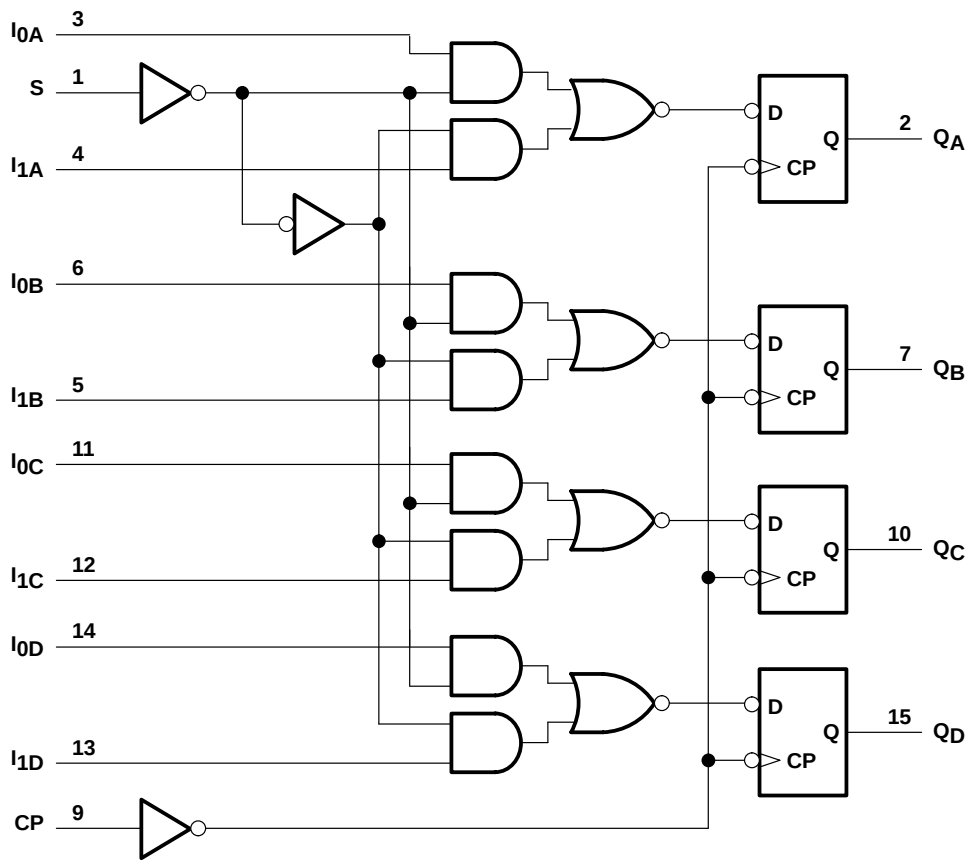
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FUNCTION TABLE

INPUTS			OUTPUT Q
S	I ₀	I ₁	
l	l	X	L
l	h	X	H
h	X	l	L
h	X	h	H

H = High logic level, h = High logic level one setup time prior to the low-to-high clock transition, L = Low logic level, l = Low logic level one setup time prior to the low-to-high clock transition, X = Don't care

logic diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1)	57°C/W
Ambient temperature range with power applied, T_A	–65°C to 135°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.75	5	5.25	V
V_{IH} High-level input voltage	2			V
V_{IL} Low-level input voltage			0.8	V
I_{OH} High-level output current			–32	mA
I_{OL} Low-level output current			64	mA
T_A Operating free-air temperature	–40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

CY74FCT399T

QUAD 2-INPUT REGISTER

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.75,	I _{IN} = −18 mA		−0.7	−1.2	V
V _{OH}	V _{CC} = 4.75	I _{OH} = −32 mA	2		V	
		I _{OH} = −15 mA	2.4	3.3		
V _{OL}	V _{CC} = 4.75,	I _{OL} = 64 mA		0.3	0.55	V
V _H	All inputs			0.2		V
I _I	V _{CC} = 5.25 V,	V _{IN} = V _{CC}			5	μA
I _{IH}	V _{CC} = 5.25 V,	V _{IN} = 2.7 V			±1	μA
I _{IL}	V _{CC} = 5.25 V,	V _{IN} = 0.5 V			±1	μA
I _{OS} [‡]	V _{CC} = 5.25 V,	V _{OUT} = 0 V	−60	−120	−225	mA
I _{off}	V _{CC} = 0 V,	V _{OUT} = 4.5 V			±1	μA
I _{CC}	V _{CC} = 5.25 V,	V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} − 0.2 V		0.1	0.2	mA
ΔI _{CC}	V _{CC} = 5.25 V, V _{IN} = 3.4 V [§] , f ₁ = 0, Outputs open			0.5	2	mA
I _{CCD} [¶]	V _{CC} = 5.25 V, One input switching at 50% duty cycle, Outputs open, V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} − 0.2 V			0.06	0.12	mA/MHz
I _C [#]	V _{CC} = 5.25 V, f ₀ = 10 MHz, Outputs open, S = Steady state	One input switching at f ₁ = 5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} − 0.2 V	0.7	1.4	mA
			V _{IN} = 3.4 V or GND	1.2	3.4	
		Four inputs switching at f ₁ = 5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} − 0.2 V	1.6	3.2	
			V _{IN} = 3.4 V or GND	2.9	8.2	
C _i				5	10	pF
C ₀				9	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

^{\S} Per TTL-driven input ($V_{IN} = 3.4 \text{ V}$); all other inputs at V_{CC} or GND

^{\parallel} This parameter is derived for use in total power-supply calculations.

^{\#} $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

CY74FCT399T QUAD 2-INPUT REGISTER

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timing requirement over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY74FCT399AT		CY74FCT399CT		UNIT
			MIN	MAX	MIN	MAX	
t _W	Pulse duration, CP high or low		5		5		ns
t _{SU}	Setup time, high or low	I _N before CP↑	3.5		3.5		ns
		S before CP↑	8.5		8.5		
t _H	Hold time, high or low	I _N after CP↑	1		1		ns
		S after CP↑	0		0		

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT399AT		CY74FCT399CT		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	CP	Q	2.5	7	2.5	6.1	ns
t_{PHL}			2.5	7	2.5	6.1	

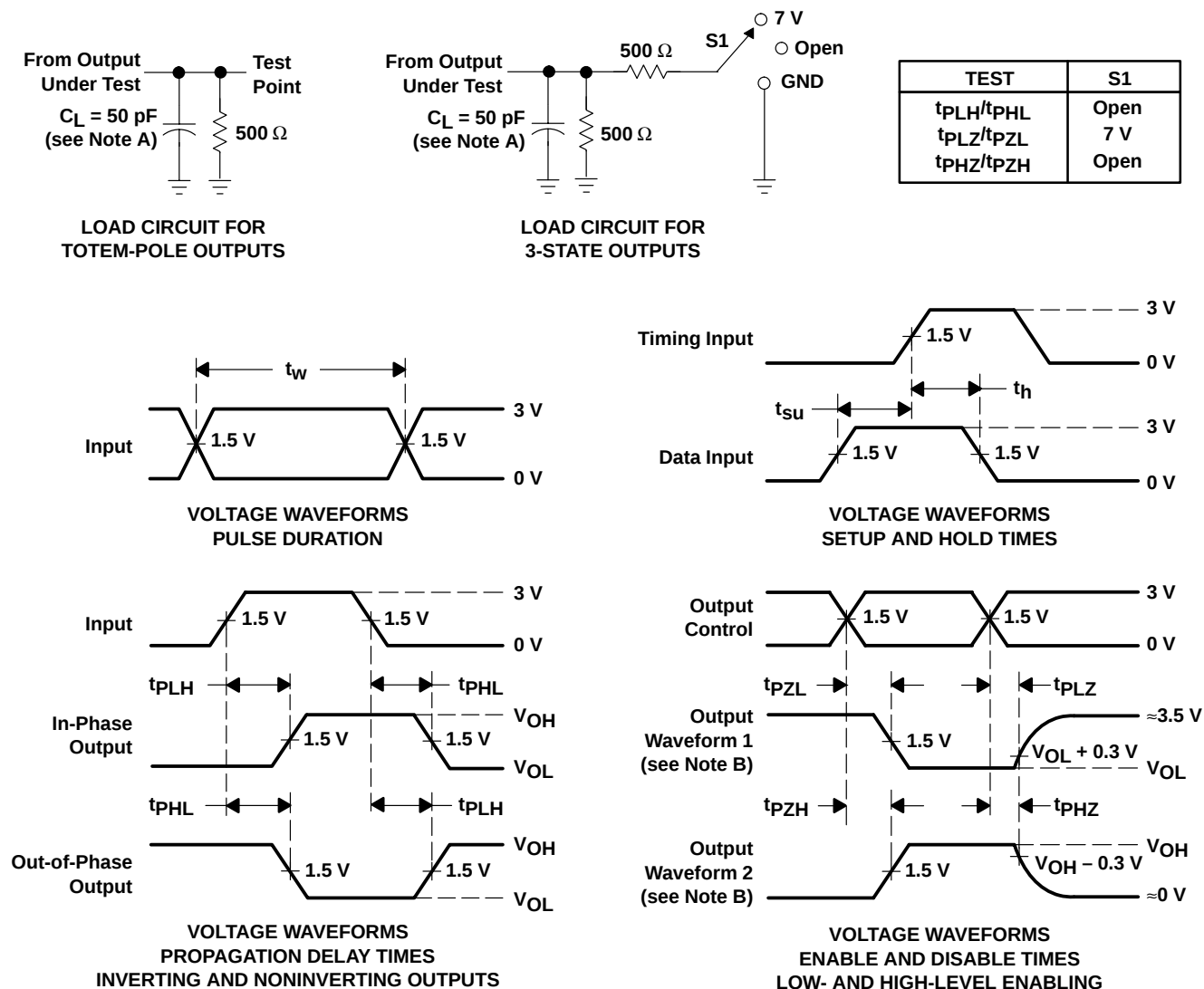


CY74FCT399T

QUAD 2-INPUT REGISTER

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT399ATSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT399A	Samples
CY74FCT399ATSOCT	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT399A	Samples
CY74FCT399CTSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT399C	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT399ATSOCT	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT399ATSOCT	SOIC	DW	16	2000	350.0	350.0	43.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CY74FCT399ATSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6
CY74FCT399CTSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6

GENERIC PACKAGE VIEW

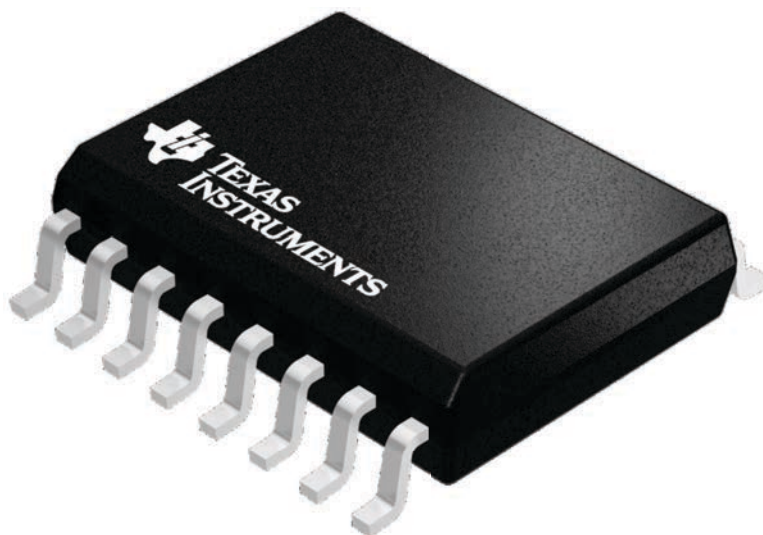
DW 16

SOIC - 2.65 mm max height

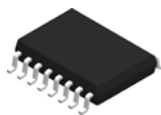
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

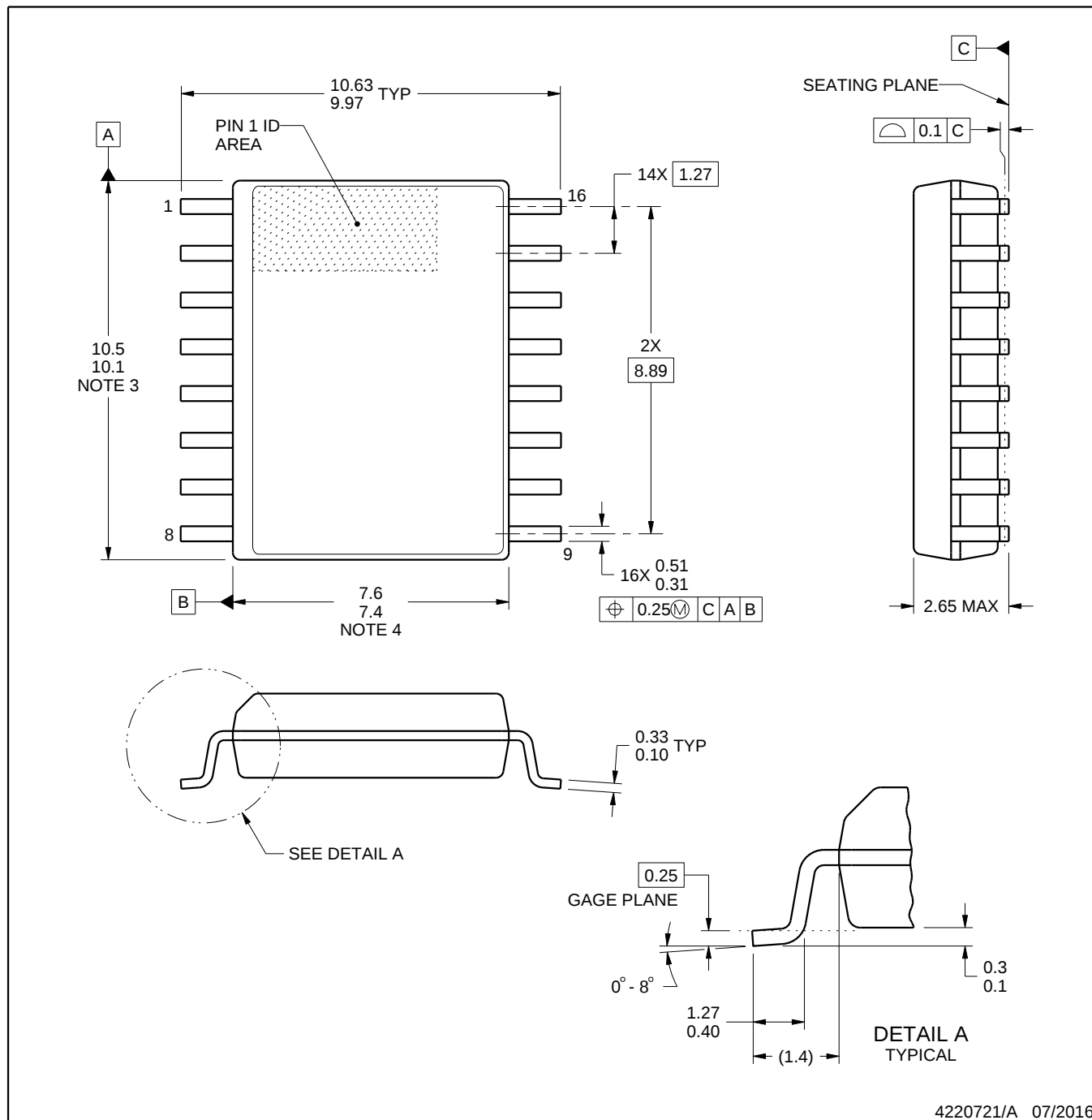


DW0016A

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

NOTES:

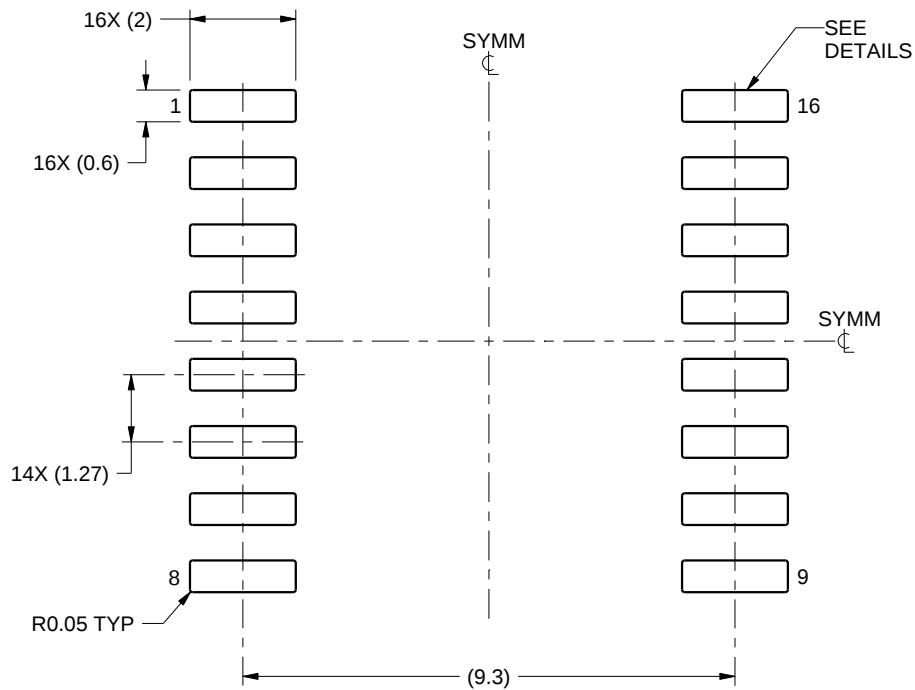
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

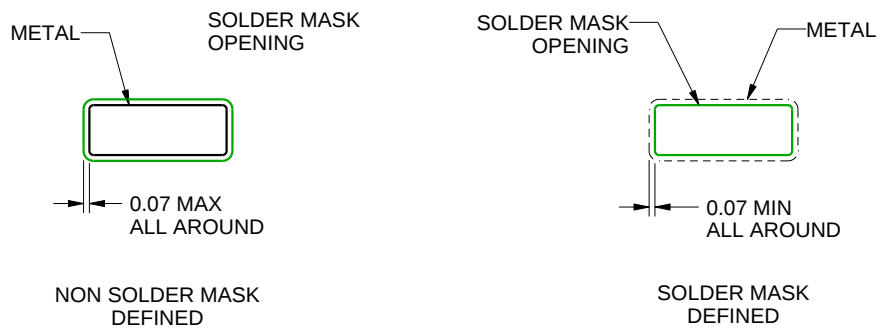
DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

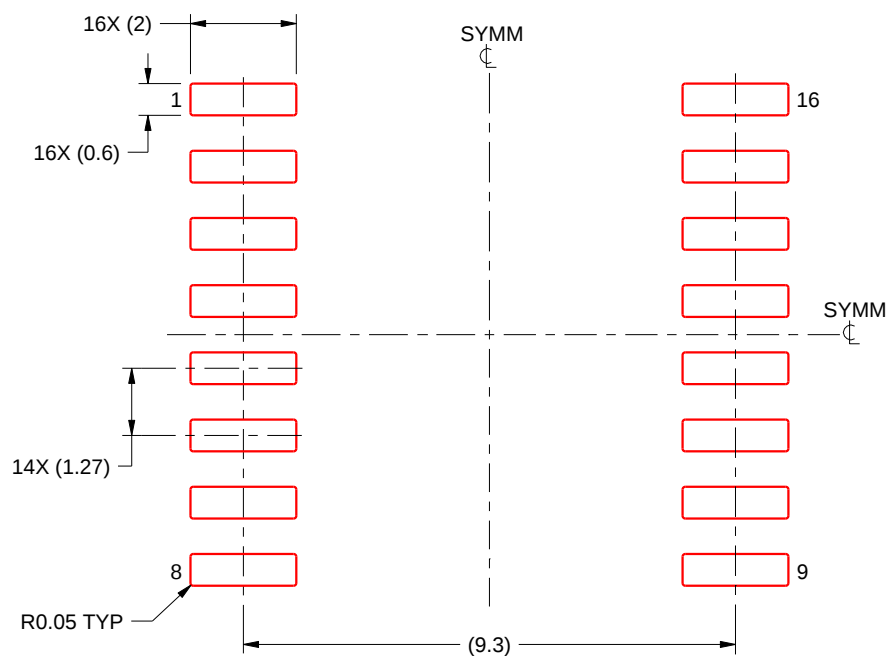
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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